

Product End-of-Life Disassembly Instructions
Product Category: Servers

Marketing Name / Model
[List multiple models if applicable.]

HPE ProLiant DL560 Gen11 Server

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPE products to remove components and materials requiring selective treatment, as defined by Directive 2012/19/EU of the European Parliament and of the Council on Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

- 1.1 Items listed below are classified as requiring selective treatment.
 1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.
 1.3 Quantities vary by product configuration

| Item Description | Notes | Quantity of items included in product |
|--|---|---------------------------------------|
| Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA) | With a surface greater than 10 sq cm | 13 |
| Batteries | All types including standard alkaline and lithium coin or button style batteries | 2 |
| Mercury-containing components | For example, mercury in lamps, display backlights, scanner lamps, switches, batteries | 0 |
| Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm | Includes background illuminated displays with gas discharge lamps | 0 |
| Cathode Ray Tubes (CRT) | | 0 |
| Capacitors / condensers (Containing PCB/PCT) | | 0 |
| Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height | Quantity varies by product configuration and power supply model selected | 16 |
| External electrical cables and cords | Quantity depends on number of power supplies, networking devices, and I/O devices | |
| Gas Discharge Lamps | | 0 |
| Plastics containing Brominated Flame Retardants | | 0 |

| Item Description | Notes | Quantity of items included in product |
|--|--|---------------------------------------|
| Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner | Include the cartridges, print heads, tubes, vent chambers, and service stations. | 0 |
| Components and waste containing asbestos | | 0 |
| Components, parts and materials containing refractory ceramic fibers | | 0 |
| Components, parts and materials containing radioactive substances | | 0 |

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

| Tool Description | Tool Size (if applicable) |
|----------------------|---------------------------|
| Torx driver | T10/T15 |
| Phillips screwdriver | #2 |
| Flathead screwdriver | Medium |
| | |
| | |

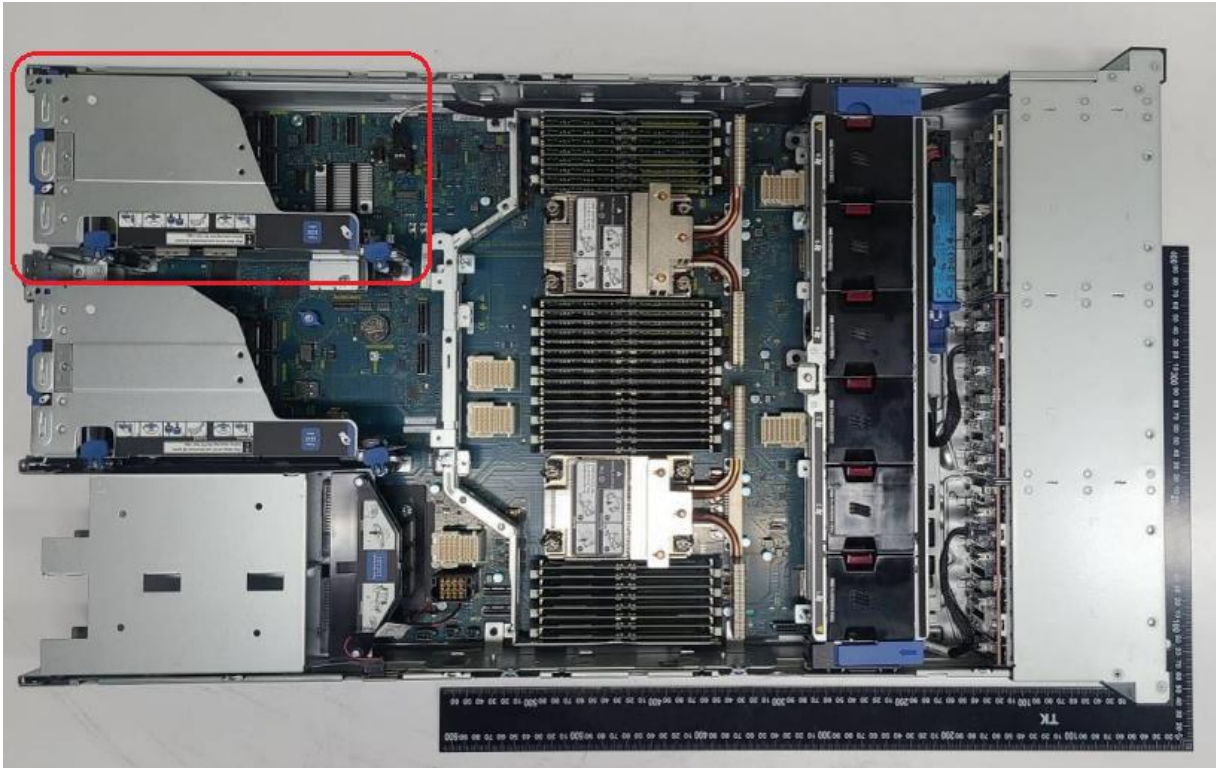
3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

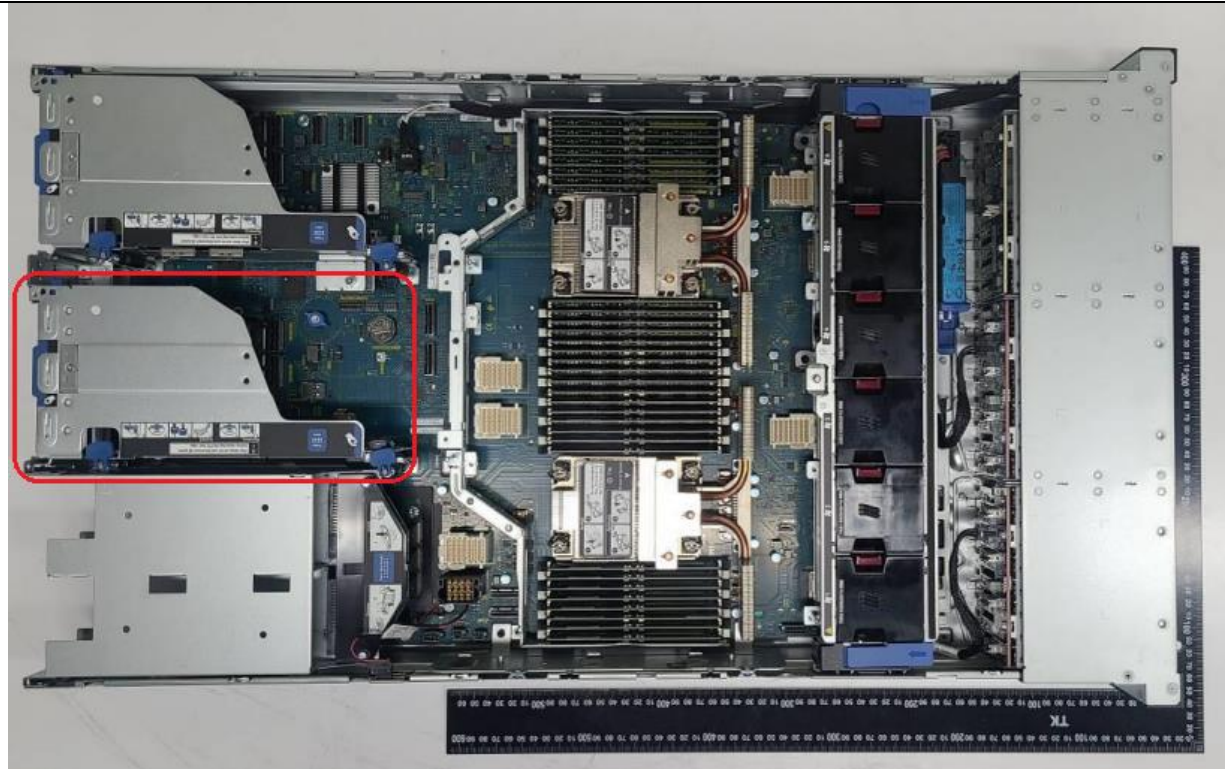
1. Remove Controller(PCBA) by Torx Driver and dispose properly.
2. Remove Shiner Card(PCBA) by Torx Driver and dispose properly.
3. Remove the top cover and locate the battery on the system board. With a medium flat head screw driver remove the battery and dispose of properly
4. Remove the top cover and locate the megacell on the system board. Remove the megacell and dispose of properly.
5. Remove Capacitors > 2.5CM of the power supply(s) from the system. With #2 Philips screw driver remove the screws securing the top cover and the heatsinks in the P/S then locate the capacitors and pry from the PCB with a medium flat head screw driver and dispose of properly

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations)

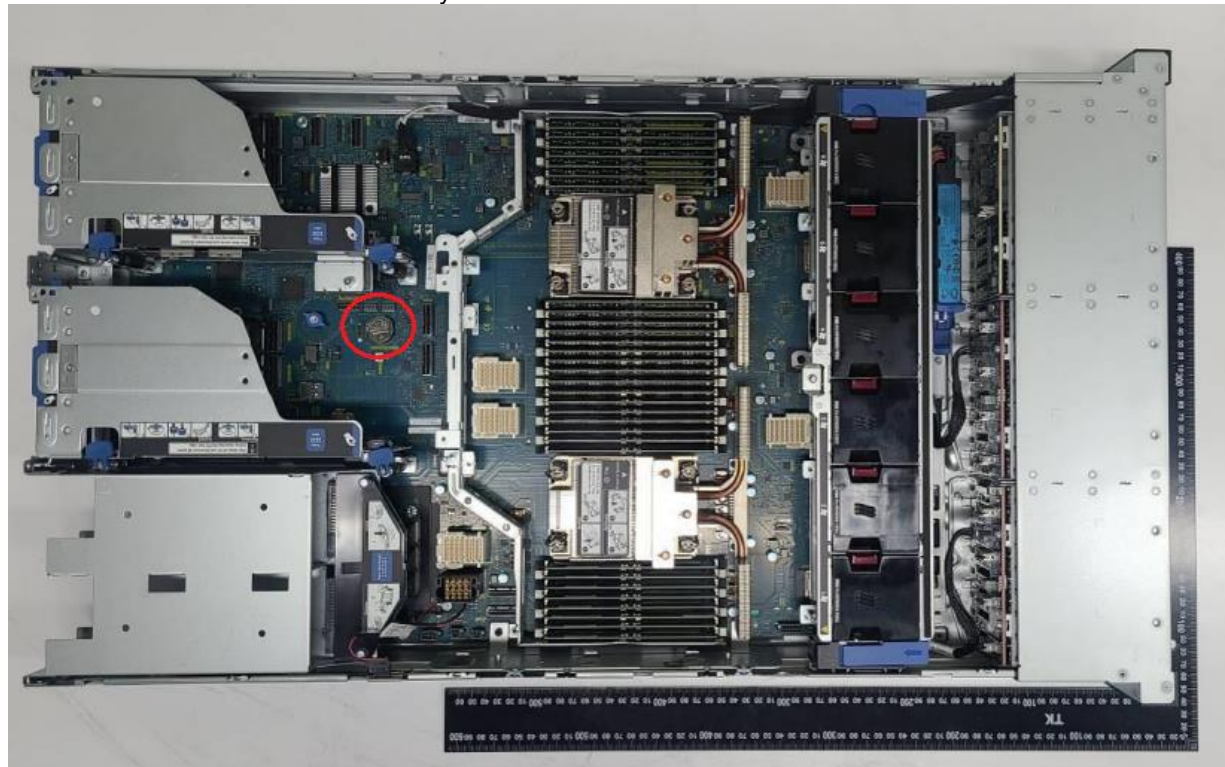
Attachment 1: Remove shiner card-PCBA



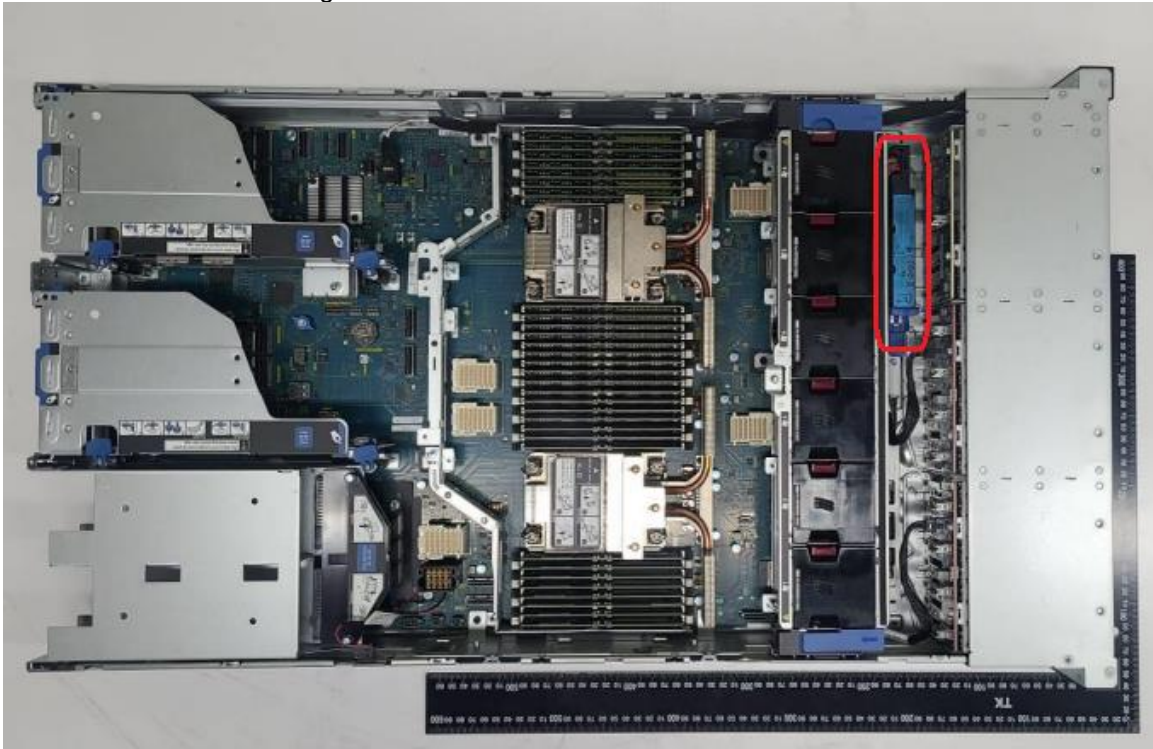
Attachment 2 Remove shiner card-PCBA



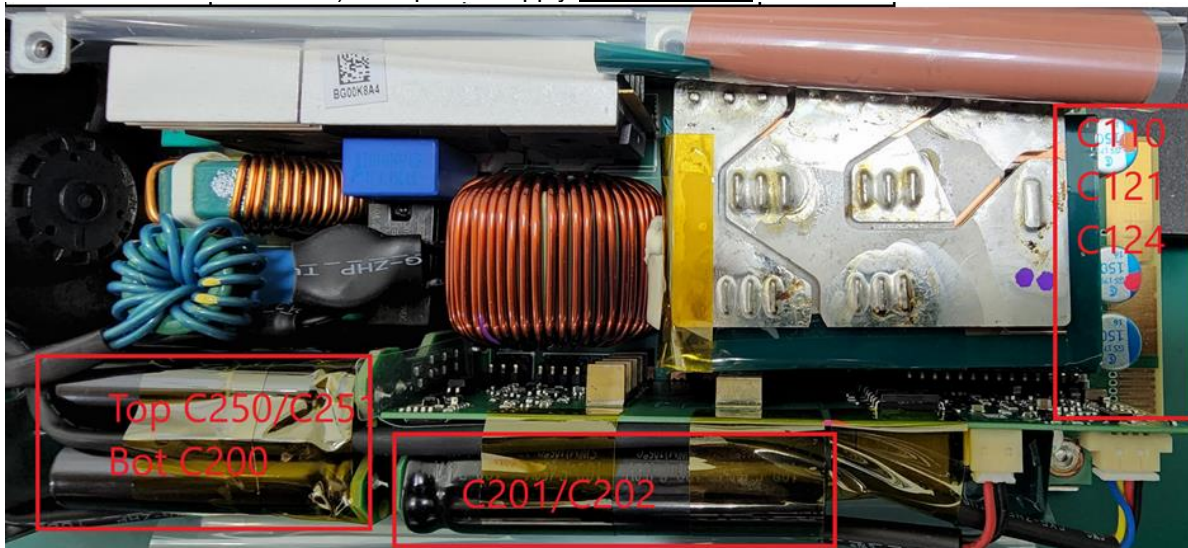
Attachment 3: Remove lithium battery



Attachment 4 : Remove mega-cell HSTNS-BB05



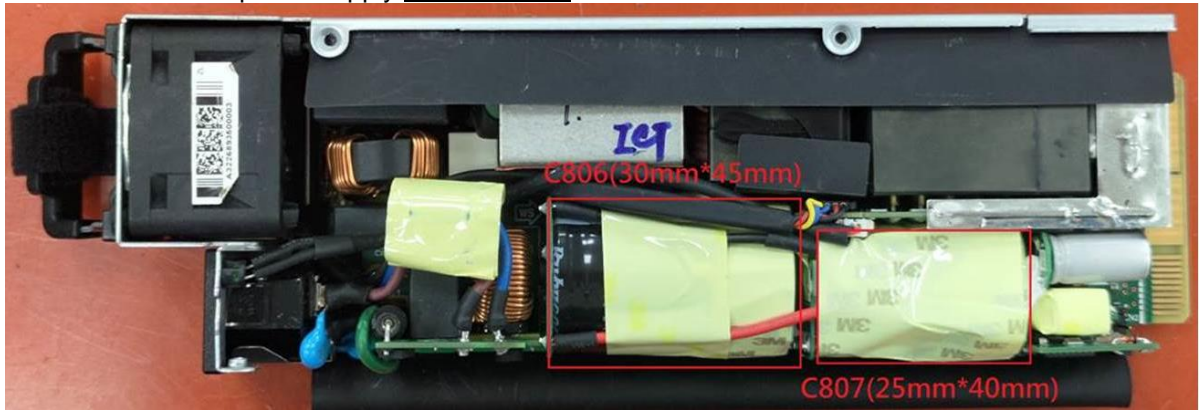
Attachment 5: Remove Electrolytic Capacitors (C201,202: 10mm*38.5mm, C200: 26mm*43mm , C250,251: 13mm*50mm) from power supply HSTNS-PR62.



Attachment 6: Remove Electrolytic Capacitor (C102: 30mm*60mm) from power supply HSTNS-PL62.



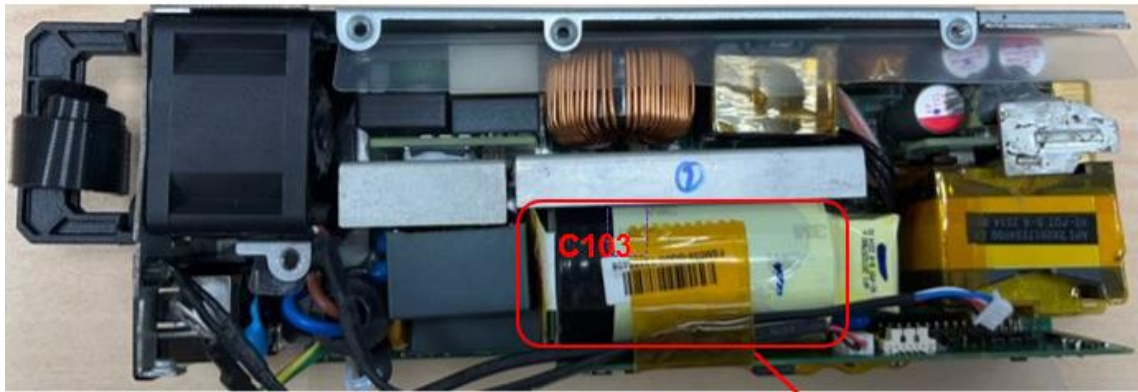
Attachment 7: Remove Electrolytic Capacitor (C806: 30mm*45mm and C807: 25mm*40mm) from power supply HSTNS-PD72.



Attachment 8: Remove Electrolytic Capacitor (C101: 30mm*70mm and C925:10mm*25mm) from power supply HSTNS-PL72.

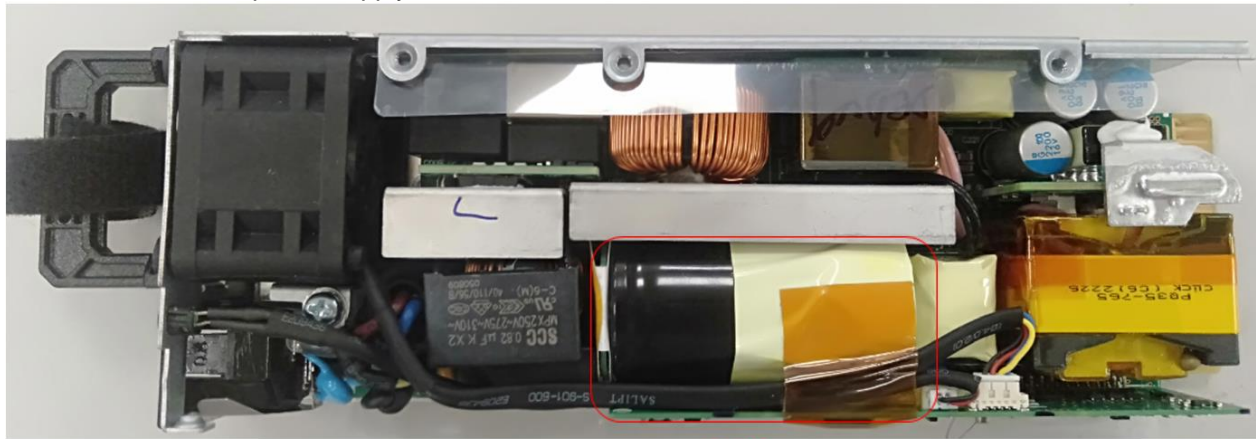


Attachment 9: Remove Electrolytic Capacitor (C103: 30mm*50 mm) from power supply HSTNS-PA67.



C103: 30*50 MM

Attachment 10: Remove Electrolytic Capacitor (C103: 30mm*50 mm) from power supply HSTNS-PD67.



C103

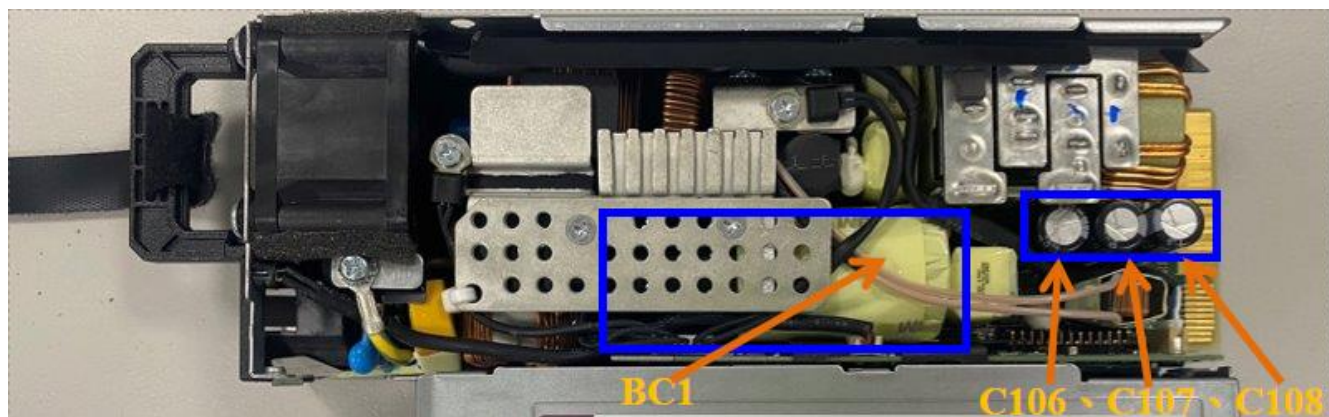
Attachment 11: Remove Electrolytic Capacitor (C103: 30mm*50 mm) from power supply HSTNS-PL67.



Attachment 12: Remove Electrolytic Capacitor (C102: 30mm*40 mm) from power supply HSTNS-PL41-1.



Attachment 13: Remove Electrolytic Capacitor (BC1: 25.4mm*60 mm and C106/C107/C108 10mm*25mm) from power supply HSTNS-PC41-1.



Attachment 14: Remove Electrolytic Capacitor (C801:25mm*60mm and C237/C238:10mm*25) from power supply HSTNS-PD41-1.

